HOSTAFORM® SXT90Z-01 XAP®

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Hostaform® acetal copolymer grade SXT90Z-01 XAP® is a UV stabilized, impact modified material available in a range of colors for automotive interior applications, while also meeting the typical low emission requirements of the automotive market. Chemical abbreviation according to ISO 1043-1: POM-HI Low emission performance (VDA 275) < 10 ppm

Product information

Resin Identification	(POM+TPU)	ISO 1043
Part Marking Code	>(POM+TPU)<	ISO 11469

Rheological properties

Melt volume-flow rate	7	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.2	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	1900	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	49	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	12	%	ISO 527-1/-2
Tensile strain at break, 50mm/min	47[PV]	%	ISO 527-1/-2
Flexural modulus	1850	MPa	ISO 178
Charpy impact strength, 23°C	N	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	N	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	11	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	7	kJ/m^2	ISO 179/1eA
Izod notched impact strength, 23°C	10	kJ/m^2	ISO 180/1A
Izod notched impact strength, -40°C	8.0	kJ/m^2	ISO 180/1A
Poisson's ratio	0.41[C]		

[PV]: Preliminary Value

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Coefficient of linear thermal expansion (CLTE), parallel	138[1]	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	139[1]	E-6/K	ISO 11359-1/-2

[1]: Temperature range: -40°C to 100°C

Physical/Other properties

Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	1380	kg/m^3	ISO 1183

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Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	190	°C
Min. melt temperature	180	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	65	°C
Min. mould temperature	60	°C
Max. mould temperature	70	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa

Characteristics

Processing	Injection Moulding
Special characteristics	High impact or impact modified, U.V. stabilised or stable to weather, Low emissions

Additional information

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying to prevent splay and odor problems.

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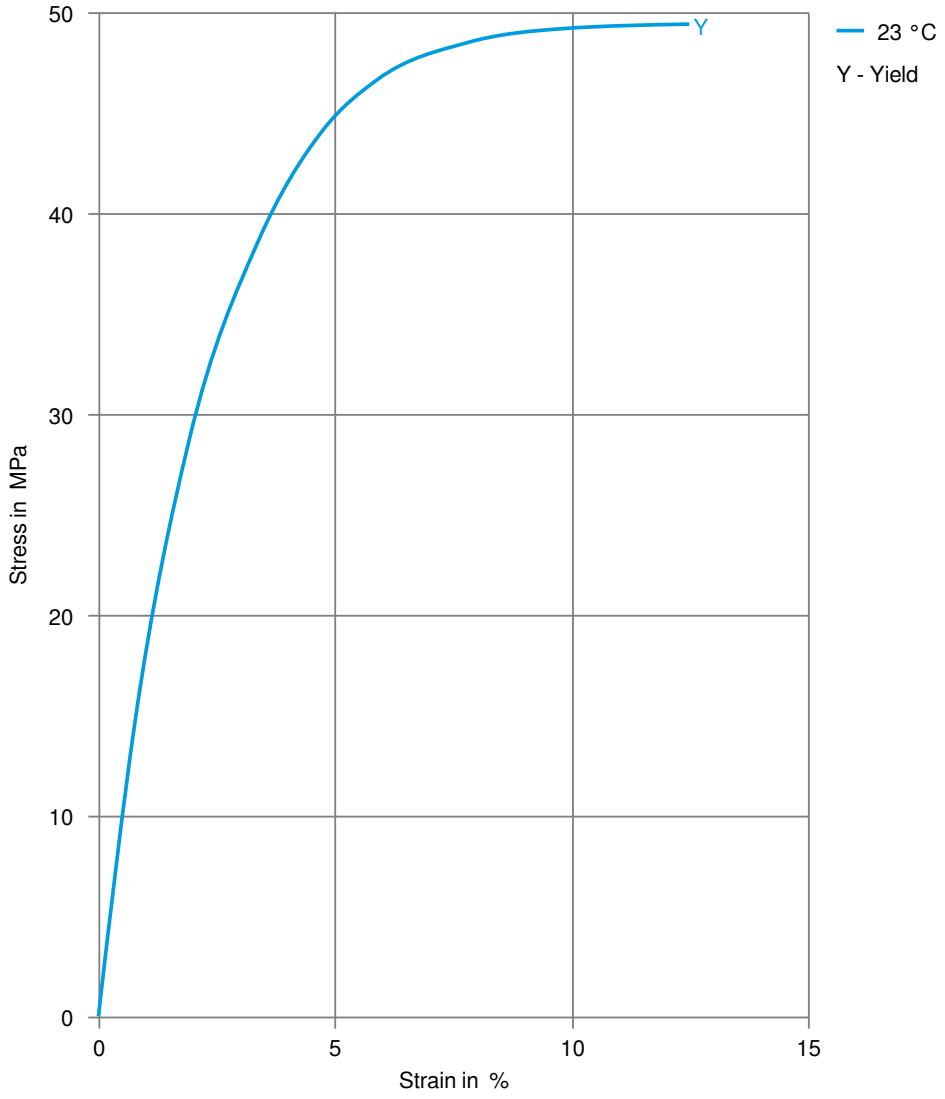
Stress-strain



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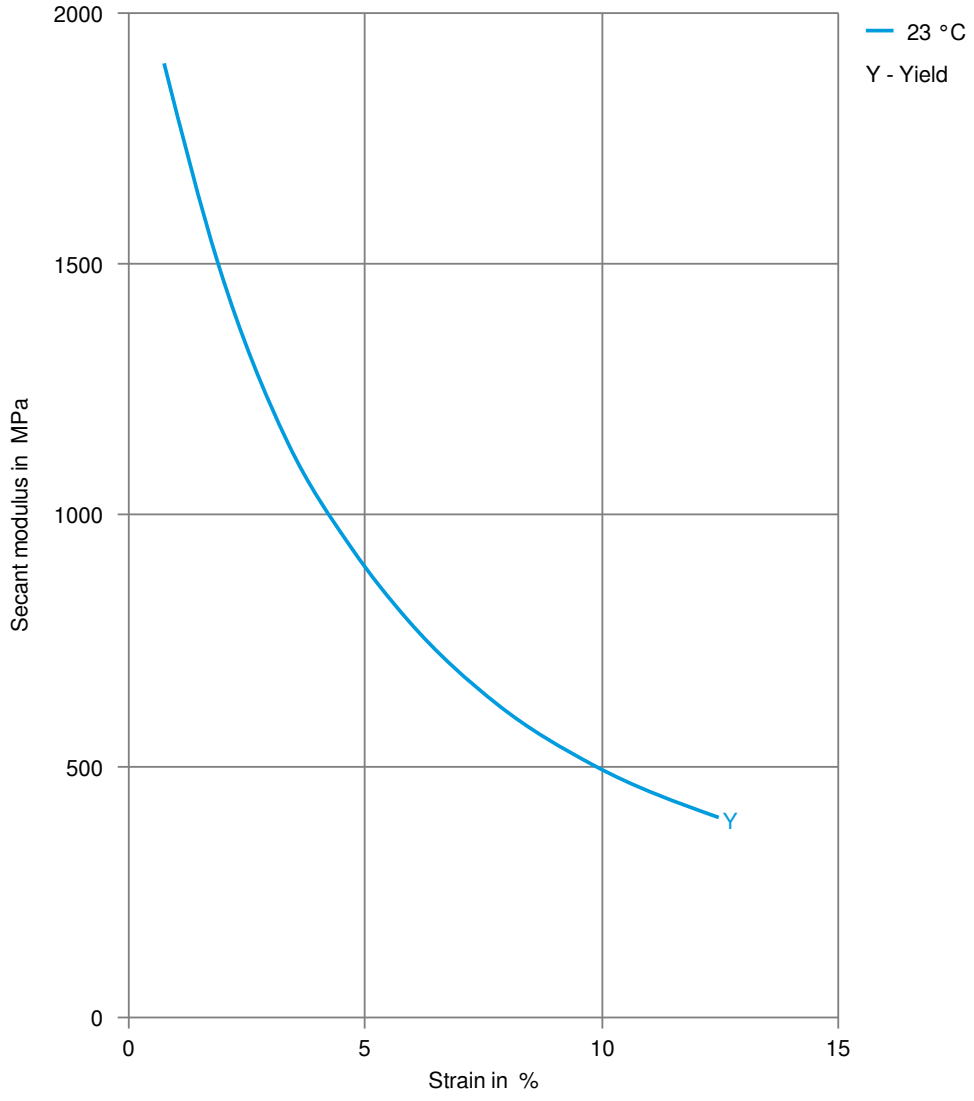
Secant modulus-strain



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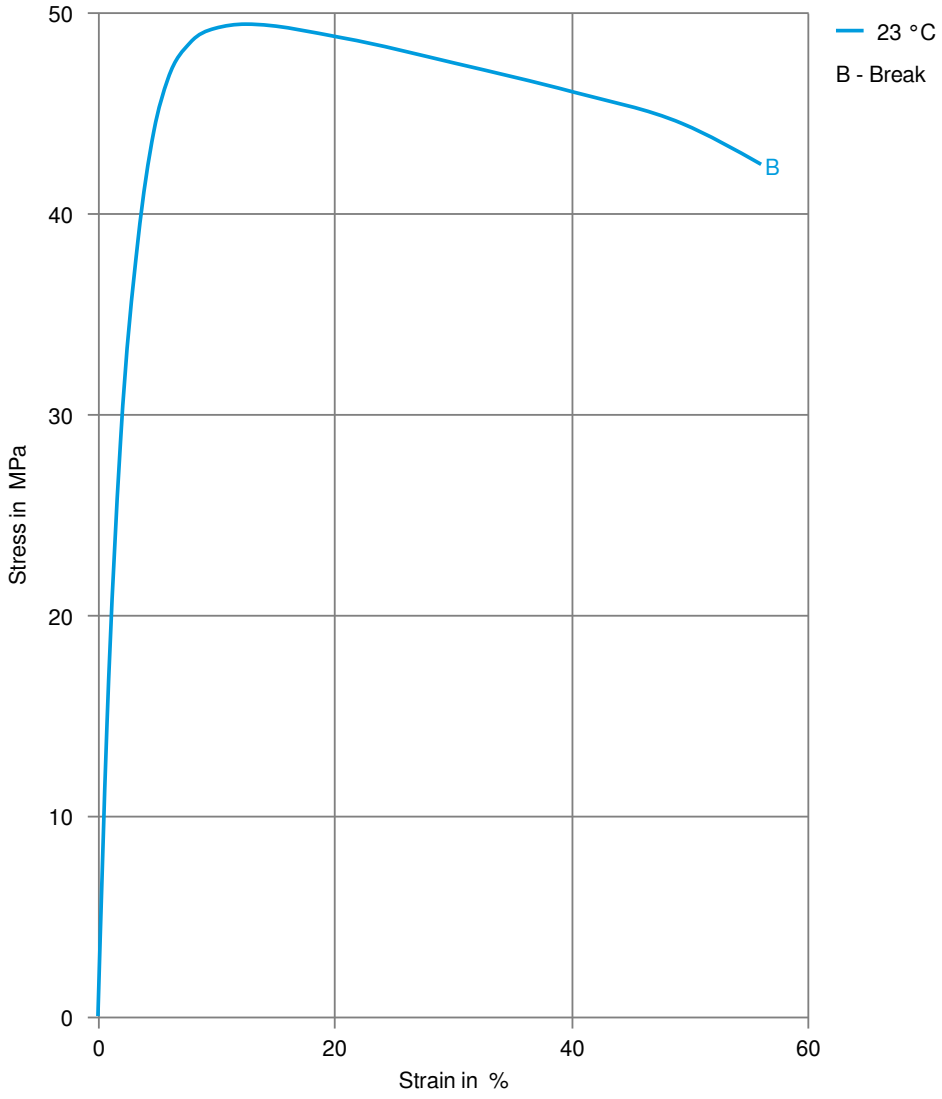
Stress-strain, 50mm/min



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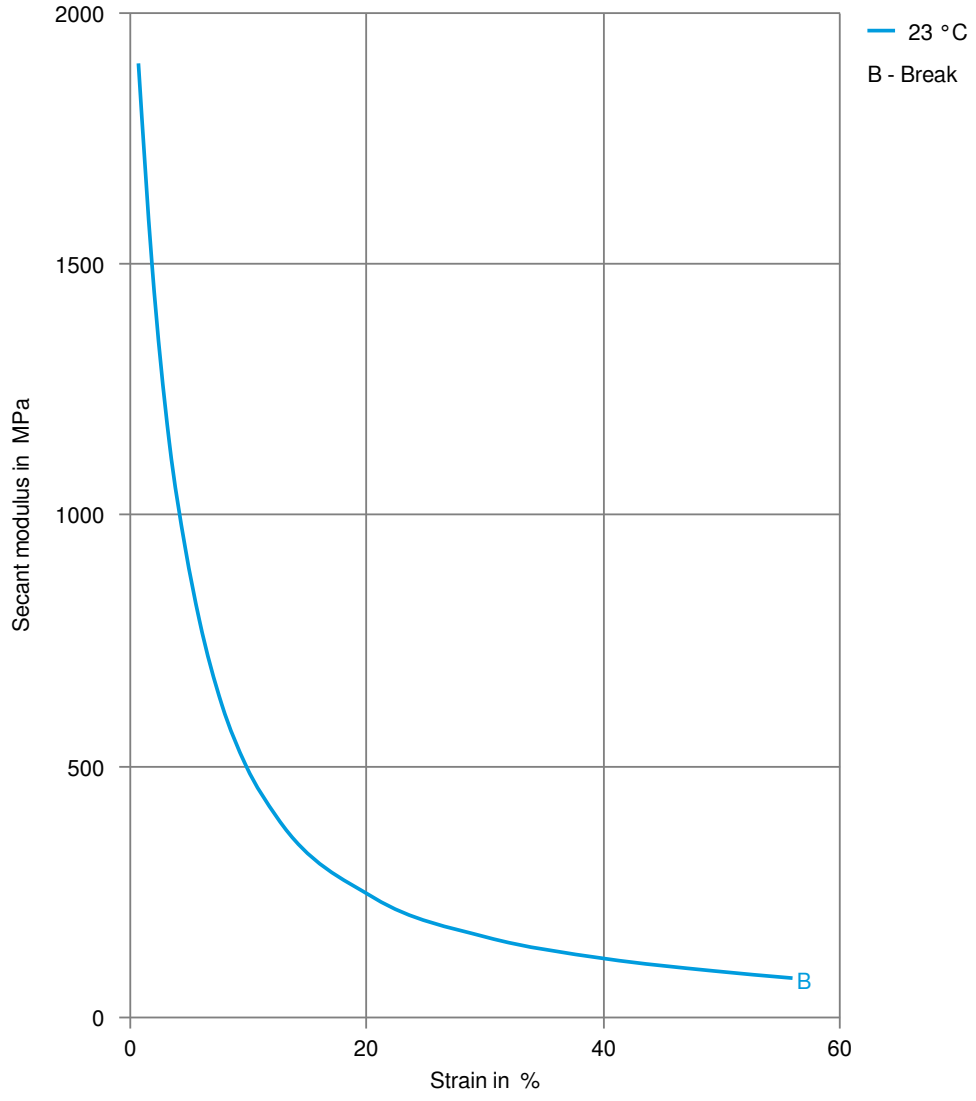
Secant modulus-strain, 50mm/min



Revised: 2024-12-03 Source: Celanese Materials Database